

**PATENT ASSIGNMENT**

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<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JI-YOON LEE	02/04/2010
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<b>State/Country:</b>	REPUBLIC OF KOREA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	29355544
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<b>Total Attachments: 1</b> source=DE1934DES_ASSIGNMENT#page 1.tif	

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**ASSIGNMENT**

WHEREAS, I, Ji-Yoon LEE, citizen of the Republic of Korea, residing at 111-1505, Hanjin Hanwha Grandville Apt., Wolgye-dong, Nowon-gu, Seoul, Republic of Korea, Republic of Korea, hereafter referred to as Applicant, has invented certain new and useful improvements in the invention:

SYNTHETIC RESIN PAPER

for which an application for a United States Patent was filed on FEB. 9, 2010

Serial No.: 29/355,544

which is identified by Baker & Hostetler, LLP Docket No. DE1934DES

for which an application for a United States Patent was executed on 02/04/10

and WHEREAS LG HAUSYS, LTD., a Korean corporation, of 20, Yeouido-doing, Yeongdeungpo-gu, Seoul, Republic of Korea, here referred to as "Assignee", is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of the sum of One Dollar (US\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNORS, has sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my signature.

Date: Feb. 4, 2010 이 지 윤 L.S.

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